

Electronic Patent Application Fee Transmittal

Application Number:	10591476			
Filing Date:	01-Sep-2006			
Title of Invention:	Copper film deposition method			
First Named Inventor/Applicant Name:	Yasuhiko Kojima			
Filer:	Michael A. Makuch/Cynthia Johnson			
Attorney Docket Number:	33082M343			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1650